

SUN TECTRO CO., LTD.



President	Mr. Hiroshi Hamao
Established	1990
Capital	30,000,000 JPY
Employees	115
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Quality Management Certifications

○ISO 9001

Office / Plant

Hiroshima headquarters and factory, Mokage office

Core Technologies and Capabilities

The development, design, and manufacture of products such as industrial electronics, electrical control equipment, and PCBs (Printed circuit boards). We also carry out the development and manufacture of carbon fiber composite materials.

Materials

Carbon fiber composite materials (thermoplastic resin, prepreg)

Using Powder Impregnated Method, we are able to provide high performance thermoplastic resin carbon fiber semipreg, and prepreg materials. Our proprietary dry powder coating method enables high performance prepreg materials such as fabric, tape, or yarn to be coated with a thermoplastic resin. As long as the resin can be made into a powder, we are able to make semipreg materials regardless of the type. Direct shaping of semipreg is also possible to provide excellent formability and thorough impregnation. This method can also be applied to thermosetting resin.

Major Customers

【Aerospace sector】 None

【Other sectors】 Japan Steel Works, Ltd.

Mitsubishi Hitachi Power Systems, Ltd.,

Kofu Meidensha Electric Mfg. Co., Ltd.

Strengths and Competitive Advantage

In 1990, our company was established from the Japan Steel Works electrical equipment assembly department. Since then, we have continued to develop, design, and manufacture a variety of products from PCBs to control panels, primarily focusing on electrical equipment for the Japanese Ministry of Defense and industrial machinery. Based on our core inverter technology, we also provide application-specific high-capacity inverters with high levels of precision and frequency. Delivering excellent cost performance, we are able to supply electrical equipment based on our high-performance and high-reliability designs for defense applications. In addition, focusing on CFRP, which is expected to have significant development in the future, we are developing semipreg materials with superior impregnation and formability using our proprietary Powder Impregnated Method.

Main Equipment

Equipment (Maker)	Capability	Number
PCB mounting equipment (I- pulse, Senju Metal)	【Production capacity】 6,000 units/month 【Board size】 Up to 250 × 400mm 【Component size】 0402	1 line
X-ray inspection equipment (Pony Industry)	【Materials size】 485 × 360mm, 10W	1
Constant temperature and humidity chamber (Espec)	【Large】 1,970D × 1,900H × 3,020W -40 to 80°C, 10 to 95% RH 【Small】 1,000D × 1,000H × 800W -70 to 150°C, 10 to 95% RH	1
Constant temperature chamber (ETAC)	600D × 600H × 75W -40 to +150°C	1
Impact tester (Shinyei Testing Machinery)	10 to 300G, 50kg	1
Vibration test machine (EMIC)	【Frequency】 2 to 400Hz 【Max. vibration level】 1,000m/s ² 【Loading weight】 150kg	1
EMI/EMC test equipment (Agilent, Amp Research)	MIL-STD-1553B, CISPR, 10KHz to 10GHz	1
Shielded room (E&C Engineering)	5,000D × 6,000W × 2,500H 10KHz to 40GHz, 80dB or higher	1
Board tester (Takaya)	Flying probe method Capable of 0.2mm pitch	1